



Telink

Telink Semiconductor (Shanghai) CO., LTD
Phone: +8621 2028 1118 Fax: 8621 5038 8081
1500 Zuchongzhi Road Bldg 3
PuDong District, Shanghai, China 201203

Composition Table

To: TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.

From: HuaTian Technology (Xi An) Co.,Ltd

Product Name: TLSR8258F1KET48A

Weight(Unit): 121.0000 mg

Date: 2023/10/17

	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	5.4150	Silicon	7440-21-3	5.4150	100.00%	4.48%	1000000
Die2	GD Die	SMIC BJ	0.2760	Silicon	7440-21-3	0.2760	100.00%	0.23%	1000000
Lead Frame	A194FH	Ningbo Kangqiang	37.8000					52.45%	
				Cu	7440-50-8	36.4770	96.50%	30.15%	965000
				Fe	7439-89-6	0.8694	2.30%	0.72%	23000
				P	7723-14-0	0.0567	0.15%	0.05%	1500
				Zn	7440-66-6	0.0756	0.20%	0.06%	2000
				Pb	7439-92-1	0.0019	0.01%	0.00%	50
				Ag	7440-22-4	0.3194	0.85%	0.26%	8450
DAF	ATB-120U	Henkel	2.8220	Modified Epoxy Resin	Proprietary	1.8625	66.0%	0.06%	
				Phenol, polymer with					
				3a,4,7,7a-tetrahydro-4,7-methano-1H-indene, glycidyl ether	119345-05-0	0.6491	23.0%	0.54%	230000
				Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	9003-36-5	0.1411	5.0%	0.12%	50000
				Aromatic polyamine	Proprietary	0.1411	5.0%	0.12%	50000
Epoxy Resin	Proprietary	0.0282	1.0%	0.02%	10000				
Epoxy	L1-403NCA	LEGEND	2.8420	Diethylene glycol monoethyl ether acetate	112-15-2	0.2842	10.00%	0.74%	
				Silica	15468-32-3	1.7052	60.00%	1.41%	600000
				Acylate resin	Proprietary	0.4263	15.00%	0.35%	150000
				Epoxy resin	Proprietary	0.3979	14.00%	0.33%	140000
				Peroxide	Proprietary	0.0284	1.00%	0.02%	10000
Wire	HS-E55	Heesung	5.6750	Silver:Wire	7440-22-4	5.3907	94.9900%	0.43%	
				Gold	7440-57-5	0.0284	0.5000%	0.02%	5000
				Palladium	7440-05-3	0.2554	4.5000%	0.21%	45000
				Platinum	7440-6-4	0.0006	0.0100%	0.00%	100
Mold Compound	CEL-9220HF	RESONAC Materials	60.5000					43%	
				Epoxy Resin 1	Trade secret	0.3025	0.50%	0.25%	5000
				Epoxy Resin 2	Trade secret	0.3025	0.50%	0.25%	5000
				Epoxy Resin 3	Trade secret	0.3025	0.50%	0.25%	5000
				Hardener	Trade secret	1.2100	2.00%	1.00%	20000
				Catalyst	Trade secret	0.0061	0.01%	0.01%	100
				Carbon black	1333-86-4	0.1210	0.20%	0.10%	2000
				Amorphous silica1	60676-86-0	53.7180	88.79%	44.40%	887900
				Amorphous silica2	7631-86-9	4.5375	7.50%	3.75%	75000
Plating	TIN	AISEN	5.6700	Tin	7440-31-5	5.6694	99.99%	2.07%	
				Others	Trade Secret	0.0006	0.01%	0.00%	100
Total			121.0000			121.0000	100%	1000000	

保存年限：三年
QRA-051-A1
保存单位：QRA

文件编号：TFM-